# **MOSFET** – Dual, N-Channel with ESD Protection, **Small Signal, SOT-563** 60 V, 310 mA

## **Features**

- Low R<sub>DS(on)</sub> Improving System Efficiency
- Low Threshold Voltage
- ESD Protected Gate
- Small Footprint 1.6 x 1.6 mm
- These are Pb-Free Devices

#### **Applications**

- Load/Power Switches
- Driver Circuits: Relays, Lamps, Displays, Memories, etc.
- Battery Management/Battery Operated Systems
- Cell Phones, Digital Cameras, PDAs, Pagers, etc.

#### MAXIMUM RATINGS (T<sub>.I</sub> = 25°C unless otherwise noted.)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	60	V
Gate-to-Source Voltage			$V_{GS}$	±20	V
Continuous Drain	Steady	$T_A = 25^{\circ}C$	I <sub>D</sub>	294	mA
Current (Note 1)	State	T <sub>A</sub> = 85°C		212	
Power Dissipation (Note 1)	Steady State		P <sub>D</sub>	250	mW
Continuous Drain	t≤5s	T <sub>A</sub> = 25°C	I <sub>D</sub>	310	mA
Current (Note 1)	l≤os	T <sub>A</sub> = 85°C		225	
Power Dissipation (Note 1)	t ≤ 5 s		P <sub>D</sub>	280	mW
Pulsed Drain Current	t <sub>p</sub> = 10 μs		I <sub>DM</sub>	590	mA
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C
Source Current (Body Diode)			IS	350	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C
Gate-Source ESD Rating (HBM, Method 3015)			ESD	1800	V

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	500	°C/W
$Junction-to-Ambient - t \le 5 s \text{ (Note 1)}$		447	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

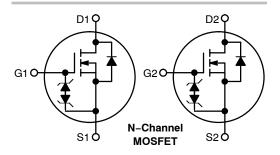
1. Surface mounted on FR4 board using 1 in sq pad size (Cu. area = 1.127 in sq [1 oz] including traces).



## ON Semiconductor®

#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> Max	
60	1.6 Ω @ 10 V	310 mA	
	2.5 Ω @ 4.5 V	STOTIA	





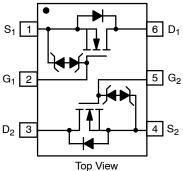
**MARKING DIAGRAM** 

S7 = Specific Device Code

M = Date Code

(Note: Microdot may be in either location)

# PINOUT: SOT-563



#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted.)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu A$		60	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	-	-		71	-	mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	T <sub>J</sub> = 25°C	-	_	1.0	μΑ
		$V_{DS} = 60 \text{ V}$	T <sub>J</sub> = 125°C	-	_	500	1
		V <sub>GS</sub> = 0 V	T <sub>J</sub> = 25°C	-	-	100	nA
		$V_{DS} = 50 \text{ V}$	T <sub>J</sub> = 85°C	-	_	100	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS}$	= ±20 V	_	_	±10	μΑ
		$V_{DS} = 0 V, V_{GS}$	= ±10 V	-	_	450	nA
		$V_{DS} = 0 V, V_{GS}$	= ±5.0 V	-	_	150	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D = 250 \mu A$		1.0	_	2.5	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>	-		_	4.0	-	mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA}$		-	1.19	1.6	Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 200 \text{ mA}$		-	1.33	2.5	1
Forward Transconductance	9 <sub>FS</sub>	$V_{DS} = 5.0 \text{ V}, I_{D} = 200 \text{ mA}$		ı	80	-	S
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 20 \text{ V}$		-	24.5	-	pF
Output Capacitance	C <sub>OSS</sub>			-	4.2	-	1
Reverse Transfer Capacitance	C <sub>RSS</sub>			-	2.2	-	
Total Gate Charge	Q <sub>G(TOT)</sub>			-	0.7	-	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	$V_{GS} = 4.5 \text{ V}, V_{D}$	s = 10 V;	_	0.1	-	1
Gate-to-Source Charge	$Q_{GS}$	I <sub>D</sub> = 200	mA	-	0.3	-	
Gate-to-Drain Charge	$Q_{GD}$			ı	0.1	-	]
SWITCHING CHARACTERISTICS (Note 4)							
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS}$ = 10 V, $V_{DD}$ = 30 V, $I_{D}$ = 200 mA, $R_{G}$ = 10 $\Omega$		-	12	-	ns
Rise Time	t <sub>r</sub>			-	7.3	-	1
Turn-Off Delay Time	t <sub>d(OFF)</sub>			-	63.7	-	1
Fall Time	t <sub>f</sub>			ı	30.6	_	1
DRAIN-SOURCE DIODE CHARACTERISTIC	s				_		
Forward Diode Voltage		V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C	-	0.8	1.2	V
	$V_{SD}$	$I_{S} = 200 \text{ mA}$ $T_{J} = 85^{\circ}$		-	0.7	-	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Surface–mounted on FR4 board using 1 in. sq. pad size (Cu. area = 1.127 in sq [1 oz] including traces).

3. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

4. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**

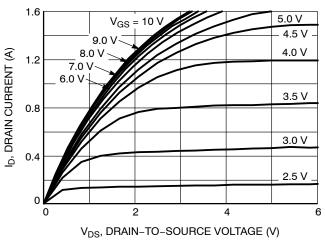


Figure 1. On-Region Characteristics

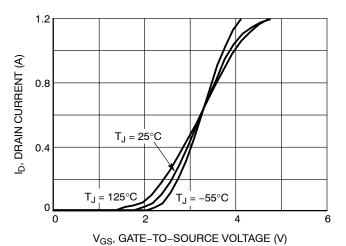


Figure 2. Transfer Characteristics

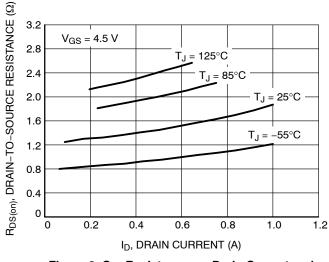


Figure 3. On–Resistance vs. Drain Current and Temperature

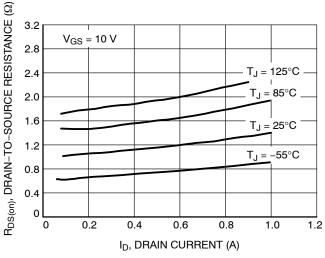


Figure 4. On–Resistance vs. Drain Current and Temperature

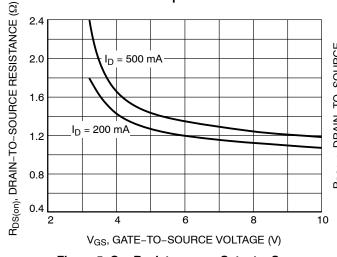


Figure 5. On-Resistance vs. Gate-to-Source Voltage

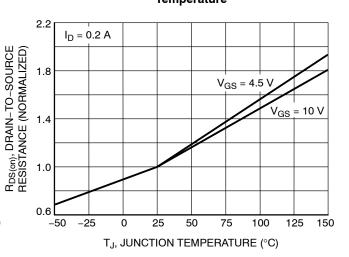


Figure 6. On–Resistance Variation with Temperature

## **TYPICAL CHARACTERISTICS**

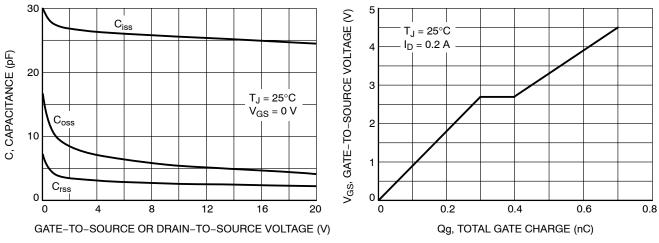


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

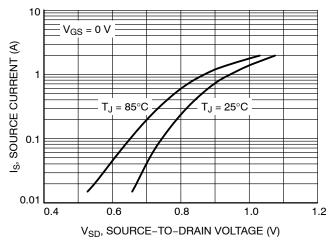


Figure 9. Diode Forward Voltage vs. Current

#### **ORDERING INFORMATION**

Device	Package	Shipping
NTZD5110NT1G	SOT-563 (Pb-Free)	4000 / Tape & Reel
NTZD5110NT5G	SOT-563 (Pb-Free)	8000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



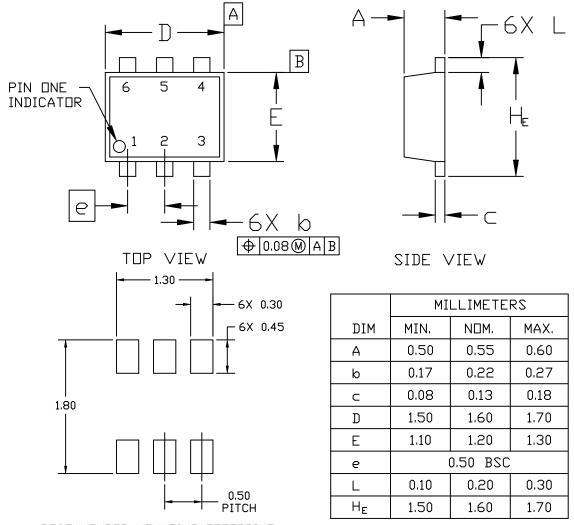


#### SOT-563, 6 LEAD CASE 463A ISSUE H

**DATE 26 JAN 2021** 

#### NOTES:

- I. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



#### RECOMMENDED MOUNTING FOOTPRINT\*

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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## **SOT-563, 6 LEAD**

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**DATE 26 JAN 2021** 

STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1	STYLE 2: PIN 1. EMITTER 1 2. EMITTER 2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1	STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 4. CATHODE 2 5. CATHODE 2 6. ANODE/ANODE
STYLE 4: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 5: PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE 5. CATHODE 6. CATHODE	STYLE 6: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE	STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SDURCE 5. DRAIN 6. DRAIN	STYLE 9: PIN 1. SDURCE 1 2. GATE 1 3. DRAIN 2 4. SDURCE 2 5. GATE 2 6. DRAIN 1
STYLE 10: PIN 1. CATHODE 1 2. N/C 3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1	STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	

# GENERIC MARKING DIAGRAM\*



XX = Specific Device CodeM = Month Code= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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